

Features

The plastic package carries Underwriters Laboratory
Flammability Classification 94V-0
Idea for printed circuit board
Glass passivated junction chip
Low reverse leakage
High forward surge current capability
High temperature soldering guaranteed
260°C/10 seconds at terminals

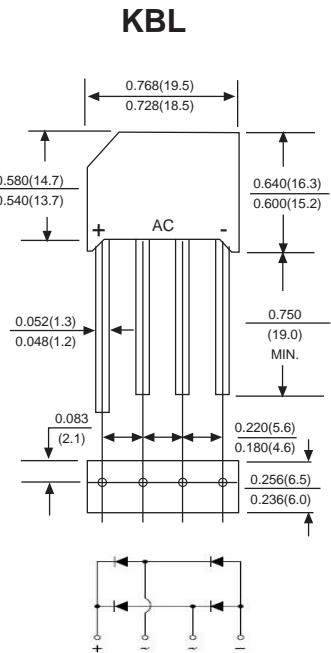
Mechanical Data

Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any



Dimensions in inches and (millimeters)

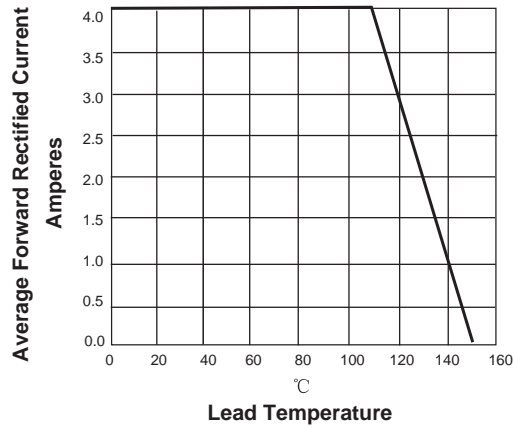
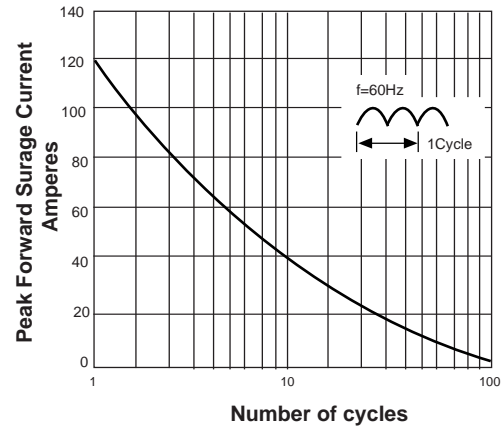
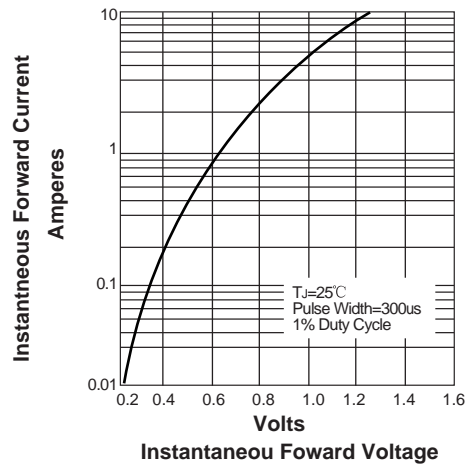
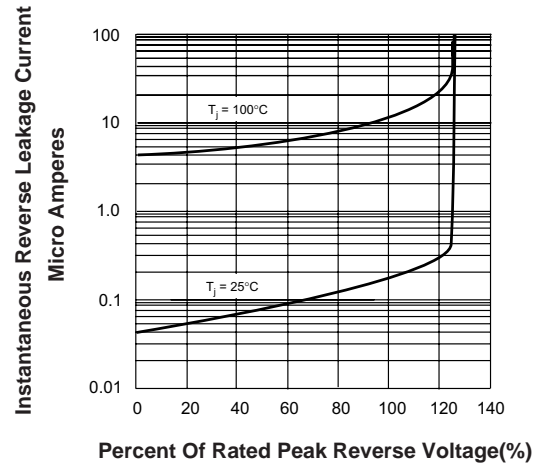
Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz,resistive or inductive load,
for capacitive load current derate by 20%.

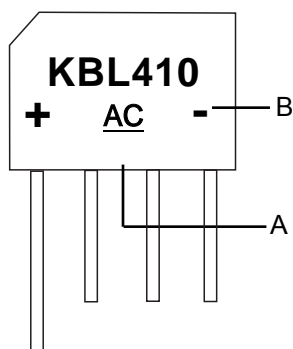
Parameter	SYMBOLS	KBL410	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC blocking voltage	V_{DC}	1000	V
Maximum average forward rectified current with heatsink	$I_{(AV)}$	4.0	A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	120.0	A
Rating for fusing ($t=8.3ms$, $T_a=25^{\circ}C$)	I_t^2	59.8	A^2s
Maximum instantaneous forward voltage at 4.0A	V_F	1.10	V
Maximum DC reverse current $T_A = 25^{\circ}C$ at rated DC blocking voltage $T_A = 100^{\circ}C$	I_R	5.0 200	μA
Typical junction capacitance (Note 1)	C_J	38.0	pF
Typical thermal resistance	R_{QA}	55.0	$^{\circ}C/W$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150	$^{\circ}C$

Note: 1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

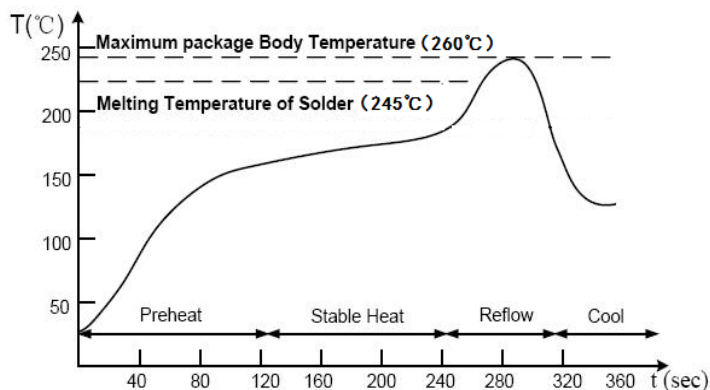
FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS


Marking



Symbol	Explanation
A	Polarity Symbol
B	Product Name

Suggested Soldering Temperature Profile



Note

Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
 The device can be exposed to a maximum temperature of 260°C for 10 seconds.
 Devices can be cleaned using standard industry methods and solvents.
 If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

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